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Validation and application of crystal plasticity simulations to study effect of process-specific defects in additively manufactured polycrystalline materials

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Presenter biography

Saikumar "Sai" Yeratapally

Work Experience:



Research engineer at National Institute of Aerospace (NIA) (10/2017- current) Post-doctoral Research Associate at NIA (3/2016 – 10/2017)

Education:

Ph.D. in Aeronautics and Astronautics Engineering from Purdue University (12/2015)

M.S. in Mechanical Engineering from Carnegie Mellon University (12/2010)

B.E. (Honors) in Mechanical Engineering from Birla Institute of Technology and Science (Goa, India) (8/2009)

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Research Interests:

Microstructure-performance linkage using crystal plasticity models Effect-of-defects in additively manufactured polycrystalline materials

Motivation

 Fatigue crack initiation (FCI) in polycrystalline materials is primarily dependent on microstructure, inclusion and defect attributes, in addition to other factors

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- Linking defect/microstructure attributes to failure mechanisms and hence performance is essential for rapid qualification

- Crystal plasticity (CP) simulations provide a platform to quantitatively link defect/microstructure attributes to performance
- Validation of CP models is important to be able to quantitatively understand the underpinning mechanisms of crack initiation



- Additive manufacturing (AM) modeling challenge
 - Comparing crystal plasticity finite element (CPFE) predictions with high-energy Xray measurements
- CP-based investigation of process-specific defects Ti-6AI-4V alloy

AM modeling challenge: Build configuration



<u>Material / AM Process</u>: Inconel 625 (IN625) produced through Laser powder-bed fusion (L-PBF)
<u>Machine</u>: EOS M280
<u>Powder</u>: Commercially available IN625 gas atomized powder
<u>Processing parameters</u>: Nominal processing parameters
<u>Machining</u>: The sample was fully machined by wire electrical discharge machining (EDM)
<u>Post processing</u>: Stress relieved (SR)+ heat treated (HT)+ hot isostatic pressing (HIP), no surface treatment

Source: ARFL's AM Challenge Series

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AM modeling challenge: High energy X-ray diffraction CAV 2021



Variants of high-energy X-ray diffraction (HEDM) technique:

1) near-field HEDM (nf-HEDM): provides data to reconstruct individual grain morphologies

2) far-field HEDM (ff-HEDM): provides grain average orientations, elastic strains and centroids

AM modeling challenge: Problem statement



<u>Challenge problem</u>: Given the stress strain curve, serial-sectioned and reconstructed 3D microstructure, predict grain-average elastic strain tensor for 28 "challenge" grains at six different macroscopic load states, S1 through S6

Source: ARFL's AM Challenge Series

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• Additive manufacturing (AM) modeling challenge

- Comparing crystal plasticity finite element (CPFE) predictions with high-energy Xray measurements
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Crystal plasticity (CP) for structure-property linkage

ScIFEN: Scalable Implementation of Finite Elements by NASA



ε_{γγ} 3% 2% 1% ScIFEN¹ is built on PETSc²

- Leverages a suite of data structures and routines to achieve scalability.
- Utilizes open-source libraries like MOAB³ and HDF5⁴ for parallel I/O operations.
- Scales well over thousands of processers, compared to commercial packages
- Includes phenomenological CP models
- ➢ Interfaces with DREAM.3D⁵, Gmsh⁶ and SPPARKS⁷
- 3D microstructure* of IN625 obtained from serial-sectioning has 29,662 grains
- Finite element mesh has ~85 million degrees of freedom
- Global strain applied in YY direction: 1%
- <u>CP model</u>: Strain-gradient based⁸
- <u>Simulation time</u>: ~44 hours on 640 Intel Xeon E5-2670 processors
- 1. https://software.nasa.gov/software/LAR-18720-1
- 2. Scalable solutions for PDEs, <u>www.mcs.anl.gov/petsc/</u>
- 3. Mesh-Oriented dataBAse, http://sigma.mcs.anl.gov/moab-library/
- 4. Parallel file I/O, www.hdfgroup.com

- 5. DREAM.3D http://dream3d.bluequartz.net/
- 6. Gmsh, https://gmsh.info/
- 7. SPPARKS, https://spparks.github.io/
- 8. Acharya et al. (2000), J. Mech. Phys. Solids, 48(10), pp:2213-2230

Boundary conditions:

- Fully fixed bottom (-Y) face
- Free X and Z faces
- Applied Y-displacement on top (+Y) face

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*Source of 3D microstructure: AFRL AM challenge series https://materials-data-facility.github.io/MID3AS-AM-Challenge/

CP predictions vs. ff-HEDM measurements

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- > There is a good agreement between CP predictions and ff-HEDM measurements in the elastic regime (S1-S3)
- Deviations start to develop in plastic regime (S4-S6)

Discrepancy 1: Boundary conditions







Boundary conditions:

- Fully fixed bottom (-Y) face
- Free X and Z faces
- Applied Y-displacement on top (+Y) face

Discrepancy 1: Boundary conditions

Strain maps of total strain in YY direction, generated at global strain of 1%



Non-cumulative L2 norm calculated at each macroscopic load state, S_k

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S_k is macroscopic stress state;

 g_n is grain ID

Discrepancy 2: Stress relaxation in grains

ff-HEDM measurement of evolution of YY component of grain-average elastic strain in each of the 28 grains

CPFE prediction of evolution of YY component of grain-average elastic strain in each of the 28 grains

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Observation: Phenomenological CP model used is unable to predict stress relaxation

Discrepancy 2: Stress relaxation in grains

- Heatmap showing strain drop in grains
- Heatmap created using ff-HEDM data.





Observation: Stress relaxation is predominant in the plastic regime and is non-existent in the elastic regime

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Illustration: Grain-level stress relaxation in Ti-7AI



Setup of creep experiment at advanced photon source (APS)

Stress relaxation during creep loading at 85% of the yield stress

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> Corresponding slip band developed at the location of the grain

Source: Beaudoin et al. Physical Review B. 96, 174116 (2017)

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Journal: Integrating Materials and Manufacturing Innovation (IMMI)

Special Issue: Metal Additive Manufacturing Modeling Challenge Series 2020



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Fatigue crack initiation at pores

AlSi10Mg, L-PBF Ti6AI4V, EBM Ti6AI4V, WAAM Ø 288 µm Ø 328 um Diameter [mm] (a) (a) crack detection (k) 0.3781 0.3152 0.2523 Cycles since o 0.1894 0.1265 0.0636 1 mm mm mm Biswal et al. (2019) Additive Manufacturing 28:517–52 Williams et al. (2017) Scientific Report | 7: 7308 12 mm .

Du Plessis et al. (2020) Materials and Design 187 (2020) 108385.

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EBM: electron beam melting WAAM: wire arc additive manufacturing L-PBF: Laser powder-bed fusion



x Oo Οσ ⊙ σ 🗳 0 cycles 73,000 cvcles 71,000 cycles 70,000 cycles A357-T6, Cast 69,000 cvcles 66,000 cycles 64,000 cvcles 53,000 cycles 40,000 cvcles 0 cycles $500 \ \mu m$ 200 µm $200 \ \mu m$ Pore 1 (b) Pore : Munoz et al. (2016) Scientific Reports | 7:45239 Free Surface

Influence of pore neighborhood

Equivalent plastic strain map (at 1% global strain)

L-PBF process-specific pores in as-built Ti-6AI-4V alloy, obtained from backscatter electron images of metallographic sections



Strain map in local neighborhood of *pore 1*



Strain map when there is no pore

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Pore 1 is embedded in a "hard" grain

Strain map in local neighborhood of *pore 2*



Strain map when there is no pore



Pore 2 is embedded in a "soft" grain

Influence of pore neighborhood

Strain map in local neighborhood of *pore 1*



Strain map in local neighborhood of *pore 2*



Strain map when there is no pore



Strain map when there is no pore





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Observation: Pore fully embedded in "soft" grain accumulates significant plastic strain in its vicinity compared to a similar sized pore located within a "hard" grain

- Grain-average elastic strain measurements from crystal plasticity finite element (CPFE) are compared with far-field high energy X-ray diffraction (ff-HEDM) measurements.
 ScIFEN's CPFE solver predictions (in the elastic regime) agree with ff-HEDM measurements
 - The results qualitatively agree in the elastic regime, but increased level of discrepancy is observed in the plastic regime

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- ➢Sources of discrepancy between CPFE and ff-HEDM are discussed
- CP simulations are used to understand the influence of local microstructure on the accumulation of plastic strain.
 - Pore fully embedded in "soft" grain accumulates significant plastic strain compared to a similar sized pore located within a "hard" grain
- Ongoing work to validate and apply high-fidelity CP models will be used to develop certification by analysis

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Thank you.

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